

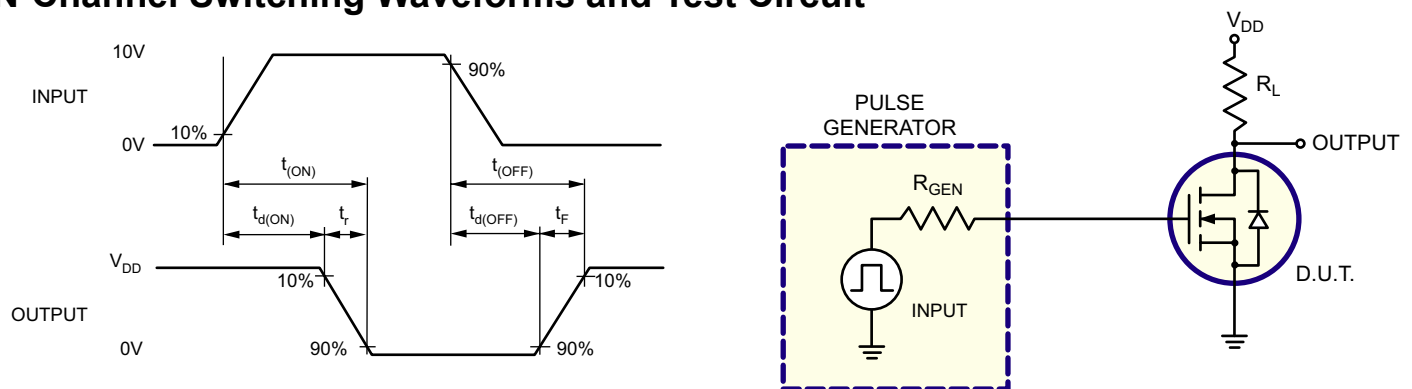
N-Channel Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise specified)

Sym	Parameter	Min	Typ	Max	Units	Conditions
BV_{DSS}	Drain-to-source breakdown voltage	200	-	-	V	$V_{GS} = 0V, I_D = 100\mu A$
$V_{GS(th)}$	Gate threshold voltage	0.6	-	2.0	V	$V_{GS} = V_{DS}, I_D = 1.0mA$
$\Delta V_{GS(th)}$	Change in $V_{GS(th)}$ with temperature	-	-	-4.5	mV/ $^\circ\text{C}$	$V_{GS} = V_{DS}, I_D = 1.0mA$
I_{GSS}	Gate body leakage	-	-	100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
I_{DSS}	Zero gate voltage drain current	-	-	1.0	μA	$V_{GS} = 0V, V_{DS} = 100V$
		-	-	10.0	μA	$V_{GS} = 0V, V_{DS} = \text{Max rating}$
		-	-	1.0	mA	$V_{GS} = 0V, T_A = 125^\circ\text{C}$ $V_{DS} = 0.8 \text{ Max Rating}$
$I_{D(ON)}$	On-state drain current	0.6	-	-	A	$V_{GS} = 4.5V, V_{DS} = 25V$
		1.2	-	-		$V_{GS} = 10V, V_{DS} = 25V$
$R_{DS(ON)}$	Static drain-to-source on-state resistance	-	-	8.0	Ω	$V_{GS} = 4.5V, I_D = 150mA$
		-	-	7.0		$V_{GS} = 10V, I_D = 1.0A$
$\Delta R_{DS(ON)}$	Change in $R_{DS(ON)}$ with temperature	-	-	1.0	%/ $^\circ\text{C}$	$V_{GS} = 4.5V, I_D = 150mA$
G_{FS}	Forward transconductance	150	-	-	mmho	$V_{DS} = 25V, I_D = 200mA$
C_{ISS}	Input capacitance	-	-	110	pF	$V_{GS} = 0V, V_{DS} = 25V, f = 1.0MHz$
C_{OSS}	Common source output capacitance	-	-	60		
C_{RSS}	Reverse transfer capacitance	-	-	23		
$t_{d(ON)}$	Turn-on delay time	-	-	20	ns	$V_{DD} = 25V, I_D = 150mA, R_{GEN} = 25\Omega$
t_r	Rise time	-	-	15		
$t_{d(OFF)}$	Turn-off delay time	-	-	25		
t_f	Fall time	-	-	25		
V_{SD}	Diode forward voltage drop	-	-	1.8	V	$V_{GS} = 0V, I_{SD} = 200mA$
t_{rr}	Reverse recovery time	-	300	-	ns	$V_{GS} = 0V, I_{SD} = 200mA$

Notes:

1. All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: $300\mu s$ pulse, 2% duty cycle.)
2. All A.C. parameters sample tested.

N-Channel Switching Waveforms and Test Circuit



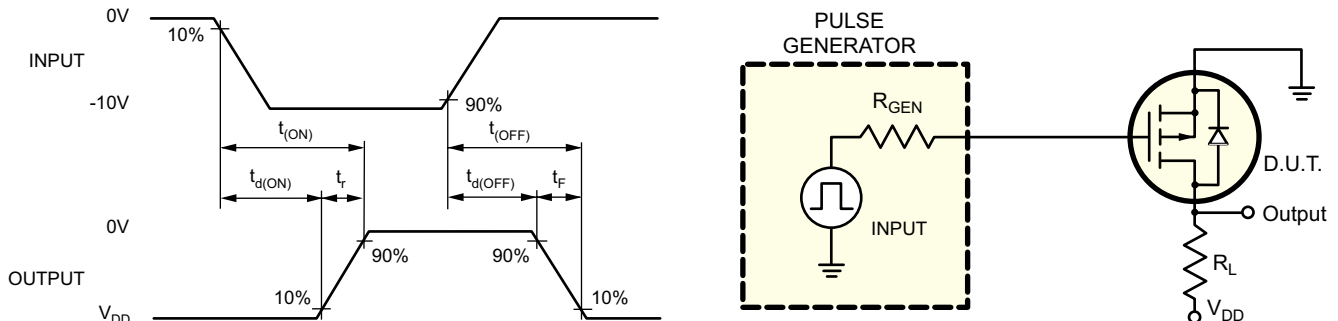
P-Channel Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise specified)

Sym	Parameter	Min	Typ	Max	Units	Conditions
BV_{DSS}	Drain-to-source breakdown voltage	-200	-	-	V	$V_{GS} = 0V, I_D = -2.0mA$
$V_{GS(th)}$	Gate threshold voltage	-1.0	-	-2.4	V	$V_{GS} = V_{DS}, I_D = -1.0mA$
$\Delta V_{GS(th)}$	Change in $V_{GS(th)}$ with temperature	-	-	4.5	mV/ $^\circ\text{C}$	$V_{GS} = V_{DS}, I_D = -1.0mA$
I_{GSS}	Gate body leakage	-	-	-100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
I_{DSS}	Zero gate voltage drain current	-	-	-10	μA	$V_{GS} = 0V, V_{DS} = \text{Max rating}$
		-	-	-1.0	mA	$V_{GS} = 0V, T_A = 125^\circ\text{C}, V_{DS} = 0.8 \text{ Max Rating}$
$I_{D(ON)}$	On-state drain current	-0.25	-0.7	-	A	$V_{GS} = -4.5V, V_{DS} = -25V$
		-0.75	-2.1	-		$V_{GS} = -10V, V_{DS} = -25V$
$R_{DS(ON)}$	Static drain-to-source on-state resistance	-	10	15	Ω	$V_{GS} = -4.5V, I_D = -100mA$
		-	8.0	12		$V_{GS} = -10V, I_D = -200mA$
$\Delta R_{DS(ON)}$	Change in $R_{DS(ON)}$ with temperature	-	-	1.7	%/ $^\circ\text{C}$	$V_{GS} = -10V, I_D = -200mA$
G_{FS}	Forward transconductance	100	250	-	mmho	$V_{DS} = -25V, I_D = -200mA$
C_{ISS}	Input capacitance	-	75	125	pF	$V_{GS} = 0V, V_{DS} = -25V, f = 1.0MHz$
C_{OSS}	Common source output capacitance	-	20	85		
C_{RSS}	Reverse transfer capacitance	-	10	35		
$t_{d(ON)}$	Turn-on delay time	-	-	10	ns	$V_{DD} = -25V, I_D = -0.75A, R_{GEN} = 25\Omega$
t_r	Rise time	-	-	15		
$t_{d(OFF)}$	Turn-on delay time	-	-	20		
t_f	Fall time	-	-	15		
V_{SD}	Diode forward voltage drop	-	-	-1.8	V	$V_{GS} = 0V, I_{SD} = -0.5A$
t_{rr}	Reverse recovery time	-	300	-	ns	$V_{GS} = 0V, I_{SD} = -0.5A$

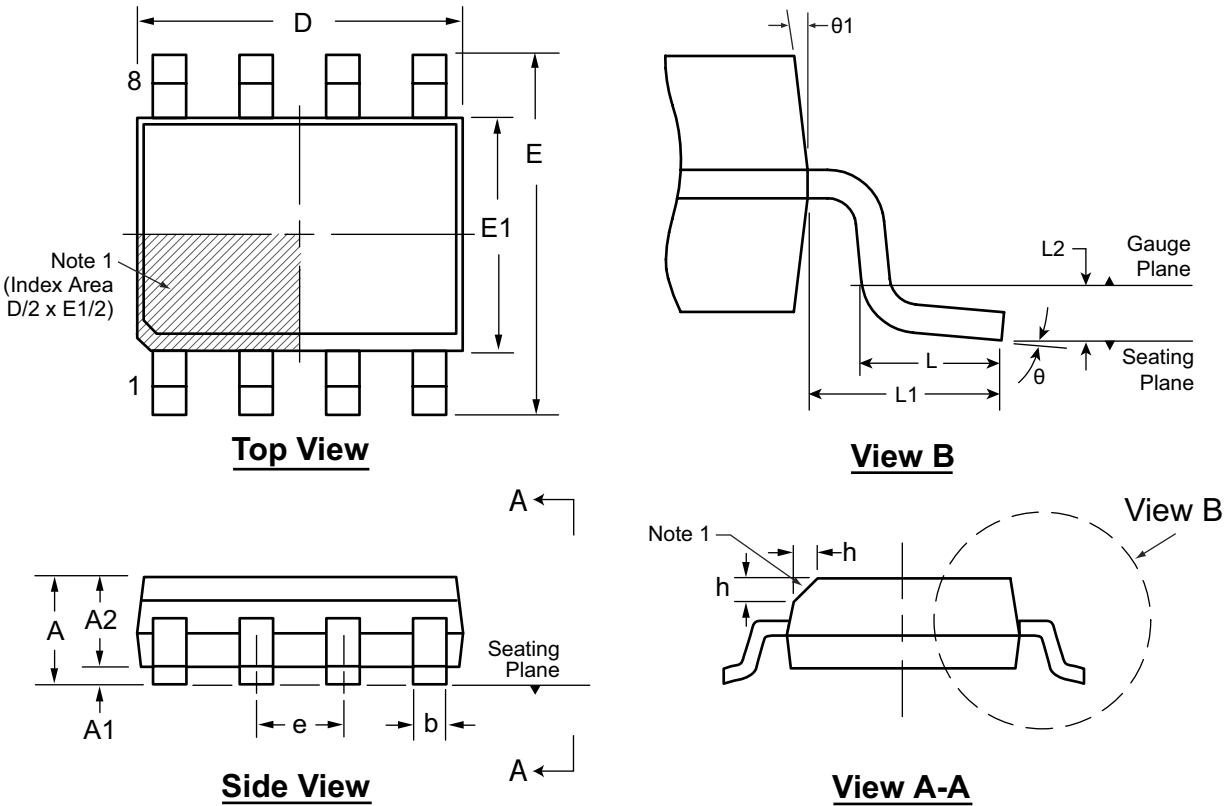
Notes:

1. All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300 μs pulse, 2% duty cycle.)
2. All A.C. parameters sample tested.

P-Channel Switching Waveforms and Test Circuit



8-Lead SOIC (Narrow Body) Package Outline (TG) 4.90x3.90mm body, 1.75mm height (max), 1.27mm pitch



Note:
1. This chamfer feature is optional. A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.

Symbol		A	A1	A2	b	D	E	E1	e	h	L	L1	L2	θ	θ1
Dimension (mm)	MIN	1.35*	0.10	1.25	0.31	4.80*	5.80*	3.80*	1.27 BSC	0.25	0.40	1.04 REF	0.25 BSC	0°	5°
	NOM	-	-	-	-	4.90	6.00	3.90		-	-			-	-
	MAX	1.75	0.25	1.65*	0.51	5.00*	6.20*	4.00*		0.50	1.27			8°	15°

JEDEC Registration MS-012, Variation AA, Issue E, Sept. 2005.
* This dimension is not specified in the original JEDEC drawing. The value listed is for reference only.
Drawings are not to scale.
Supertex Doc. #: DSPD-8SOLGTG, Version H101708.

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to <http://www.supertex.com/packaging.html>.)

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